# 

www.csem.ch

# **GalnP/Silicon dual junction solar cell** with 29.8 % certified record efficiency

M. DESPEISSE<sup>1</sup>, S. ESSIG<sup>2</sup>, C. ALLEBE<sup>1</sup>, M. A. STEINER<sup>2</sup>, J. F. GEISZ<sup>2</sup>, B. PAVIET-SALOMON<sup>1</sup>, S. WARD<sup>2</sup>, A. DESCOEUDRES<sup>1</sup>, L. BARRAUD<sup>1</sup>, V. LASALVIA<sup>2</sup>, N. BADEL<sup>1</sup>, J. CHAMPLIAUD<sup>1</sup>, A. FAES<sup>1</sup>, J. LEVRAT<sup>1</sup>, A. TAMBOLI<sup>2</sup>, P. STRADINS<sup>2</sup>, D. L. YOUNG<sup>2</sup>, C. BALLIF<sup>1</sup>.

- PV-Center, Centre Suisse d'Électronique et de Microtechnique (CSEM), CH-2002 Neuchâtel, Switzerland.
- National Renewable Energy Laboratory (NREL), Golden, Colorado, USA. 2

## From Silicon Heterojunction Solar Cells towards Silicon Based Tandem Cells

Silicon based PV devices roadmap





R&D silicon heterojunction platform set up in CSEM

	SHJ CELL	VOC mV	FF %	JSC mA/cm <sup>2</sup>	EFF %
	Full 6" PS n- type Cz 160 µm	<b>736</b> Measure	<b>79.8</b> ed with Grid	<b>38.8</b> dTouch®	22.8

# **GalnP/Silicon Heterojunction TANDEM CELL**

#### **Experimental Details:**

#### **NREL GalnP top cell:**

1.7 µm thick rear-heterojunction



### **RECORD EFFICIENCY:**

#### **Optical Analysis:**

GaInP top cell with higher EQE than SHJ bottom cell for wavelengths < 450 nm, however with EQE limited to 83% (limited diffusion length in GaInP absorber and parasitic absorption in AllnP window layer).



GaInP with active area of ~ 1  $cm^2$ grown by MOVPE on a GaAs substrate. Gold back contact grid electroplated and ZnS ARC layer evaporated on the cell backside. Sample glued to a glass slide, GaAs growth substrate and removed. Front gold contacts electroplated, n-GaAs contact layer etched in the regions without front metal, and ZnS/MgF<sub>2</sub> dual-layer antireflection coating evaporated.

#### **CSEM Silicon Heterojunction** bottom cell:

a-Si:H deposited on 230 µm thick n-Fz wafer: intrinsic/n-type doped on the rear, intrinsic/p-type doped on the front, TCO layers on both sides, rear Ag sputtering, front printed metallization grid. Special TCO patterning and metallization designed for enabling grid efficient coupling to the GaInP top cell area and glass substrate dimension.

Architecture of the GaInP/Si tandem cells developed by NREL/CSEM

![](_page_0_Picture_27.jpeg)

> 1 cm2 CSEM Silicon heterojunction solar cells patterned for integration with NREL GaInP top cells.

![](_page_0_Picture_29.jpeg)

Optical coupling optimization in the tandem and low top cell sub-bandgap absorption enable for high EQE in the bottom cell. Oscillations in EQE due to interferences caused by the top cell.

#### **J-V characteristics**:

Certified J-V curves measured at NREL, under AM1.5g spectral condition at 1 sun.

Top cell: J<sub>SC</sub> of 14.2 mA/cm<sup>2</sup>, V<sub>OC</sub> of 1.456 V for efficiency of (18.1±0.5)%.

Bottom cell: Luminescent coupling tested with bottom cell measured for top cell operating at  $J_{SC}$ ,  $P_{mpp}$  and  $V_{OC}$ .  $J_{SC}$  in the Si bottom cell 0.8 mA/cm<sup>2</sup> larger when the top cell is at  $V_{OC}$  than at  $J_{SC}$  due to radiative recombination in top cell. Accurate analysis of the cumulative tandem cell efficiency requires bottom cell JV-curve measured with top cell at its maximum power point.

Bottom cell generates  $J_{SC}$  of 22.7 mA/cm<sup>2</sup> and  $V_{OC}$  of 677 mV reaching efficiency of  $(11.7 \pm 0.4)\%$  in the tandem device.

#### Tandem performance:

The 4-terminal mechanically-stacked GaInP/Si tandem cell shows certified cumulative tandem cell efficiency of  $(29.8 \pm 0.6)$ %. This is the III-V/Si multi-junction solar cell with the highest one-sun efficiency, exceeding the theoretical efficiency limit 29.4% and the record experimental efficiency value 25.6% of a Si single-junction, 1-sun solar cell and exceeding record efficiency 1-sun GaAs device (28.8%).

eff. Voc FF JSC cell [%]  $[mA/cm^2]$ [mV] [%]

1456

14.15

GaInP top cell

87.9

 $18.1 \pm 0.5$ 

was at  $V_{OC}$ ,  $J_{SC}$  or  $P_{mpp}$ 

#### GalnP/SHJ tandem:

GaInP/Si tandem devices formed by stacking the glass slide with the top cell glued to it onto the bottom cell using a transparent adhesive. Alignment of the two subcells verified using infrared reflection before curing the adhesive.

The resulting tandem cells are 4mechanically-stacked terminal GalnP/Si tandem cells.

Schematic of the 4-terminals tandem cell construction.

![](_page_0_Picture_44.jpeg)

![](_page_0_Picture_45.jpeg)

#### **Perspectives:**

This first joint development highlighted limitations that can be overcome. For the bottom cell, low  $V_{OC}$  due to processinduced degradation during fabrication: +10-40 mV can be expected, > 700 mV in the tandem configuration (i.e. at 23 mA/cm<sup>2</sup> instead of 39 mA/cm<sup>2</sup>).  $J_{SC}$  in the Si bottom cell is 0.7 mA/cm<sup>2</sup> smaller than the maximum photon current calculated. Current in the top cell can be optimized (maximum EQE shifted up). Overall, efficiencies > 30% are potentially achievable with our tandem cell design in shortterm.

![](_page_0_Picture_48.jpeg)

F +41 32 720 5700

This work was supported by the nano-tera.ch initiative, by the Swiss Confederation, and by the U.S. Department of Energy under contract DE-EE00025783.

CSEM SA

Rue Jaquet-Droz 1

CH-2002 Neuchâtel

T +41 32 720 5111